

MC68HC16Z1CFC16 Information

[General information](#)
[Package information](#)
[Environmental and Compliance information](#)
[Replacement Parts Information](#)
[Manufacturing and Qualification information](#)
[Ordering information](#)
[Product/Process Change Notice \(PCN\)](#)
[Operating Characteristics](#)

General Information

Parameter	Value
Part Number	MC68HC16Z1CFC16
Description	16 BIT MCU, 1K RAM
Product Line	SGF16Z1
PTI	JCLF
Material Type	Tested Packaged Device
Life Cycle Description (code)	REMOVED FROM ACTIVE PORTFOLIO
Status	Migration Complete. No Longer Manufactured. View PCN and Replacement Part

Package Information

Parameter	Value
Package Description	PQFP 132 0.950*.950P.025
JEDEC Pkg Description	PQFP-G132
Package Material	Plastic
Mounting Style	Surface Mount
Tape & Reel	No

Environmental and Compliance Information

Parameter	Value
Pb-Free	No
RoHS Compliant	No
Material Composition Declaration (MCD)	Download IPC-1752 Report
RoHS Certificate of Analysis (CoA)	Download RoHS CoA Report
Package Peak Temperature (°C)	Not Available

Replacement Parts information for MC68HC16Z1CFC16

Replacement Part	Replacement Type	Replacement Reason	Status	Device Sample Availability	Device Production Availability	Further Replacements	Replacement Part Details
		REGULATORY					

MC68HC16Z1CEH16

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OR LEGAL
CHANGE

Active

Apr 2004

Apr 2004

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Manufacturing and Qualification information

Parameter	Value
Micron Size (µm)	.55
Application/Qualification Tier	COMMERCIAL, INDUSTRIAL

Ordering Information

Parameter	Value
Last Order Date	30 Jun 2006
Last Ship Date	30 Dec 2006
Export Control Classification Number (US)	EAR99
Harmonized Tariff (US) Disclaimer	8542.31.0000
Budgetary Price QTY 1000+ (\$US)	-

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
11713	Device Migration	TSPG MCD ROHS COMPLIANT NON-EXEMPT - 2	09 Jan 2006	09 Jan 2006
11462	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	14 Oct 2005	15 Oct 2005
11431	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	04 Oct 2005	05 Oct 2005
11342	Update Notification	UPDATE TO TSPG BAT3 PROBE EXPANSION	31 Aug 2005	27 Sep 2005
11262	Product Change Notice	TSPG BAT3 PROBE EXPANSION	19 Aug 2005	17 Nov 2005
11122	Product Change Notice	TSPG BAT3 PROBE EXPANSION	07 Jul 2005	05 Oct 2005
10742	Product Bulletin	KLM PACKING CHANGE FOR TRAY DEVICES	28 Mar 2005	02 Apr 2005
10021	Product Bulletin	TSPG-TECD PB-FREE PACKAGE QUALIFICATION	17 Jun 2004	18 Jun 2004
9846	Product Bulletin	TSPG-TECD PB-FREE PACKAGE QUALIFICATION	06 May 2004	07 May 2004
9048	Product Bulletin	TIC SUPPORT FOR QUALITY QUERIES IN EMEA	04 Aug 2003	05 Aug 2003
8178	Product Bulletin	HC16Z1 MOS12 QUALIFICATION	01 Nov 2002	02 Nov 2002
7258	Product Change Notice	TRANSFER PRODUCTS FROM TSC8	01 Mar 2002	10 Jun 2002
5847	Product Bulletin	NEW LOCKREEL 44MM 7" HUB 13" FLANGE	22 Aug 2000	23 Aug 2000
5182	Product Bulletin	EQUIPMENT CAPACITY IN MOS12 WAFER FAB	20 Oct 1999	21 Oct 1999
4260	Product Bulletin	TRAY SECURING PROCESS FOR SHIPPING	11 Jan 1999	12 Jan 1999
3787	Product Bulletin	ADDITION OF SOLDER PLATING BATH SOLUTION	28 Aug 1998	05 Aug 1998
3492	Product Change Notice	QUALIFICATION OF THE TSC8 82.% UDR (H35S) 68HC16Z1 MASK	11 Mar 1998	19 Jun 1998
2633	Product Change	68HC16Z1, MOS 12, (4F67V MASKSET)	08 May 1997	18 Aug 1997

Notice

Operating Characteristics

Parameter	Value
A/D Converter - Bits (bit)	10
A/D Converter - Channels	8
Ambient Operating Temperature (Ta) (Max) (oC)	85
Ambient Operating Temperature (Ta) (Min) (oC)	-40
Bus Frequency (Max) (MHz)	16
External Bus Width (bit)	16
I/O Pins	16
Internal RAM (kByte)	1
Serial Interface - Type	SCI QSPI
Supply Current (Max) (mA)	38
Supply Voltage (Typ) (V)	5
Timers - Channels	8
Timers - Size (bit)	16